

ABS Plastic-Encapsulate Bridge Rectifier

Features

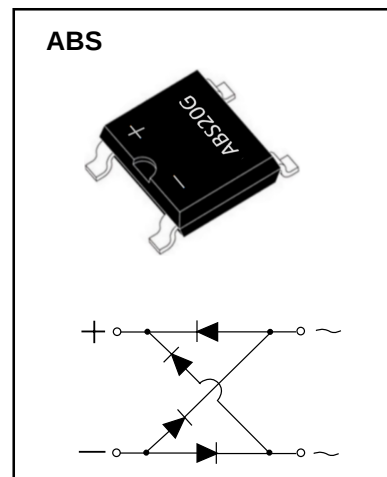
- I_O 1A
- V_{RRM} 2000V
- High surge current capability
- Glass passivated chip

Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- ABS20G



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	ABS20G
Repetitive Peak Reverse Voltage	V_{RRM}	V		2000
Maximum RMS Voltage	V_{RMS}	V		1400
Maximum DC blocking Voltage	V_{DC}	V		2000
Average Rectified Output Current	I_O	A	60Hz sine wave, R-load, $T_a=50^{\circ}C$	1.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz sine wave, 1 cycle, $T_j=25^{\circ}C$	35
Current Squared Time	I^2t	A^2S	$1ms \leq t < 8.3ms$ $T_j=25^{\circ}C$, Rating of per diode	5
Storage Temperature	T_{stg}	$^{\circ}C$		-55 ~+150
Junction Temperature	T_j	$^{\circ}C$		-55 ~+150

Electrical Characteristics ($T=25^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_{FM}=1.0A$, Pulse measurement, Rating of per diode	1.1
Peak Reverse Current	I_{RRM}	μA	$V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	5
Thermal Resistance	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient, On alumina substrate	62.5
	$R_{\theta J-L}$		Between junction and lead	25
	$R_{\theta J-C}$		Between junction and case	25

Typical Characteristics

FIG1: I_o - T_a Curve

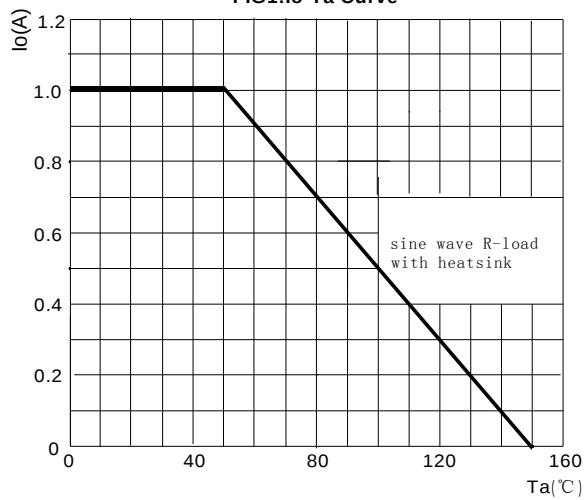


FIG2: Surge Forward Current Capability

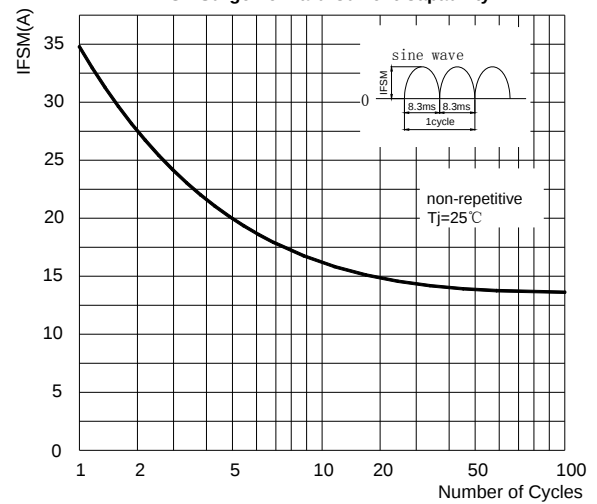


FIG3: Forward Voltage

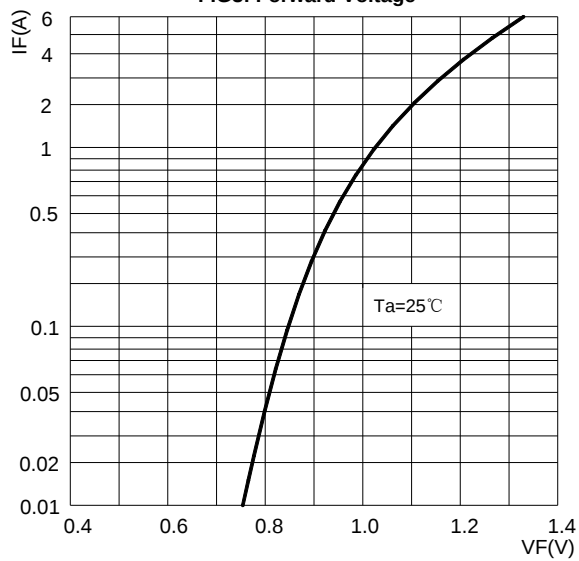
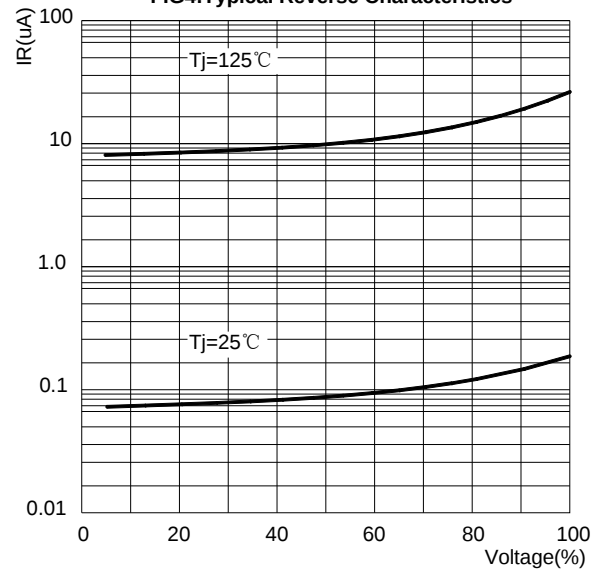
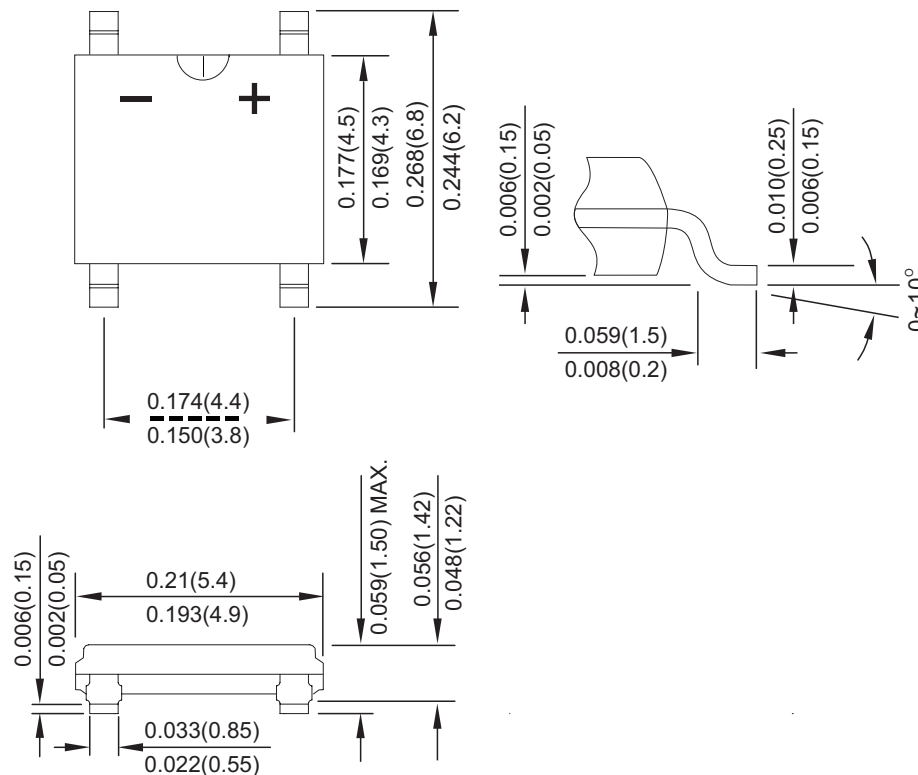


FIG4: Typical Reverse Characteristics

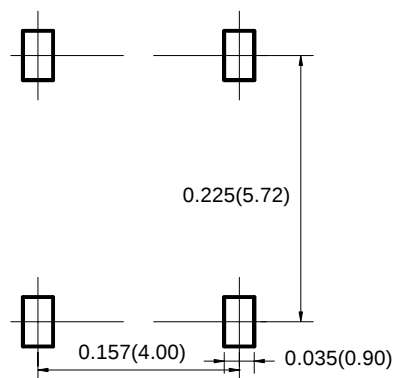


ABS Package Outline Dimensions



Dimensions in inches and (millimeters)

ABS Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices–ABS

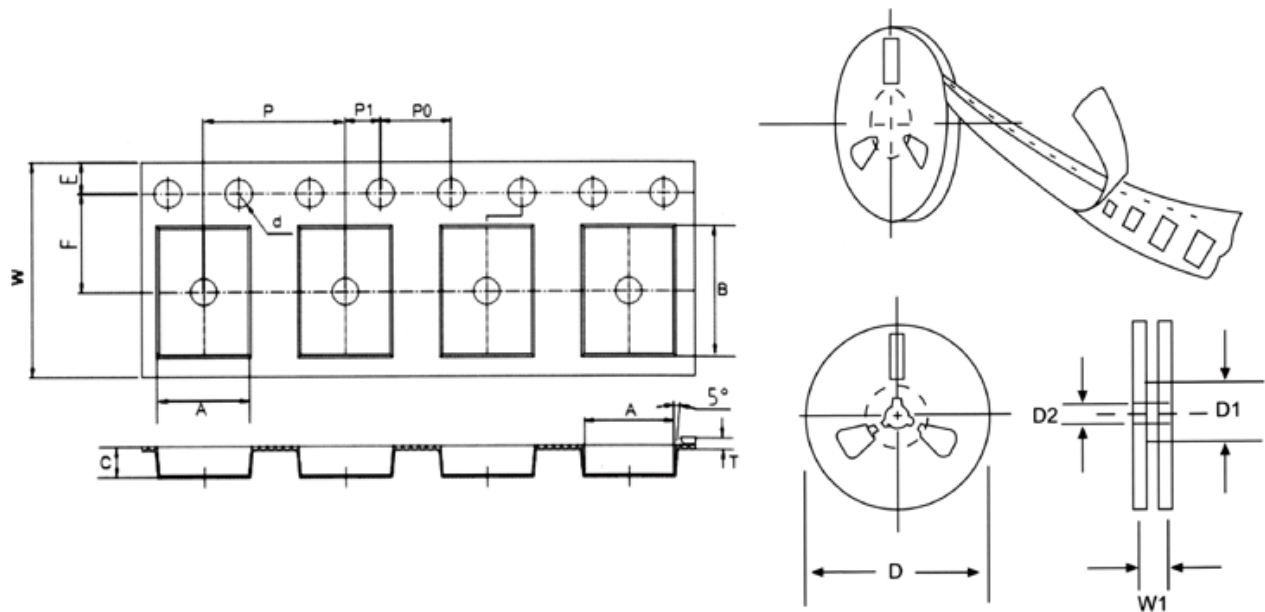


FIG : CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	ABS mm(inch)
Carrier width	A	5.40±0.1(0.213±0.004)
Carrier length	B	6.90±0.05(0.272±0.002)
Carrier depth	C	2.10±0.1(0.083±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.10-0.70(0.004-0.028)
Tape width	W	12.0±0.3/-0.1(0.472±0.004)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.